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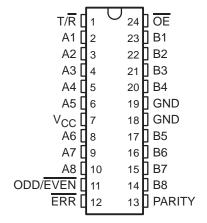
- State-of-the-Art *EPIC-IIB™* BiCMOS Design **Significantly Reduces Power Dissipation**
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per **JEDEC Standard JESD-17**
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$
- **High-Impedance State During Power Up** and Power Down
- Flow-Through Architecture Optimizes PCB Layout
- High-Drive Outputs (-32-mA I_{OH}, 64-mA I_{OI})
- **Package Options Include Plastic** Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

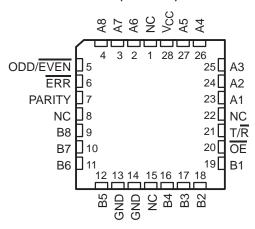
'ABT657A The transceivers have eight noninverting buffers with parity-generator/ checker circuits and control signals. transmit/receive (T/\overline{R}) input determines the direction of data flow. When T/\overline{R} is high, data flows from the A port to the B port (transmit mode); when T/\overline{R} is low, data flows from the B port to the A port (receive mode). When the output-enable (OE) input is high, both the A and B ports are in the high-impedance state.

Odd or even parity is selected by a logic high or low level on the ODD/EVEN input. PARITY carries the parity-bit value; it is an output from the parity generator/checker in the transmit mode and an input to the parity generator/checker in the receive mode.

SN54ABT657A . . . JT PACKAGE SN74ABT657A . . . DW OR NT PACKAGE (TOP VIEW)



SN54ABT657A...FK PACKAGE (TOP VIEW)



NC - No internal connection

In the transmit mode, after the A bus is polled to determine the number of high bits, PARITY is set to the logic level that maintains the parity sense selected by the level at ODD/EVEN. For example, if ODD/EVEN is low (even parity selected) and there are five high bits on the A bus, PARITY is set to the logic high level so that an even number of the nine total bits (eight A-bus bits plus parity bit) are high.

In the receive mode, after the B bus is polled to determine the number of high bits, the error (ERR) output logic level indicates whether or not the data to be received exhibits the correct parity sense. For example, if ODD/EVEN is high (odd parity selected), PARITY is high, and there are three high bits on the B bus, ERR is low, indicating a parity error.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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SCBS192E - JANUARY 1991 - REVISED JUNE 1997

description (continued)

When V_{CC} is between 0 and 2.1 V, the device is in the high-impedance state during power up or power down. However, to ensure the high-impedance state above 2.1 V, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN54ABT657A is characterized for operation over the full military temperature range of -55° C to 125° C. The SN74ABT657A is characterized for operation from -40° C to 85° C.

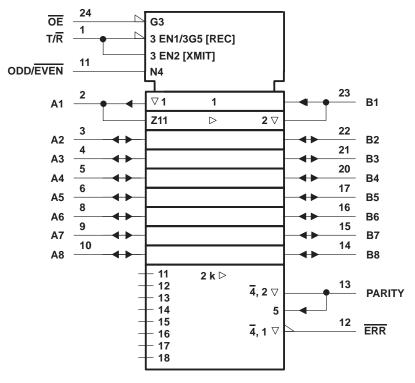
FUNCTION TABLE

TOROTOR TABLE										
NUMBER OF A OR B		INPL	JTS	1/0		OUTPUTS				
INPUTS THAT ARE HIGH	ŌĒ	T/R	ODD/EVEN	PARITY	ERR	OUTPUT MODE				
	L	Н	Н	Н	Z	Transmit				
	L	Н	L	L	Z	Transmit				
02469	L	L	Н	Н	Н	Receive				
0, 2, 4, 6, 8	L	L	Н	L	L	Receive				
	L	L	L	Н	L	Receive				
	L	L	L	L	Н	Receive				
	L	Н	Н	L	Z	Transmit				
	L	Н	L	Н	Z	Transmit				
1, 3, 5, 7	L	L	Н	Н	L	Receive				
1, 3, 5, 7	L	L	Н	L	Н	Receive				
	L	L	L	Н	Н	Receive				
	L	L	L	L	L	Receive				
Don't care	Н	Χ	X	Z	Z	Z				



SCBS192E - JANUARY 1991 - REVISED JUNE 1997

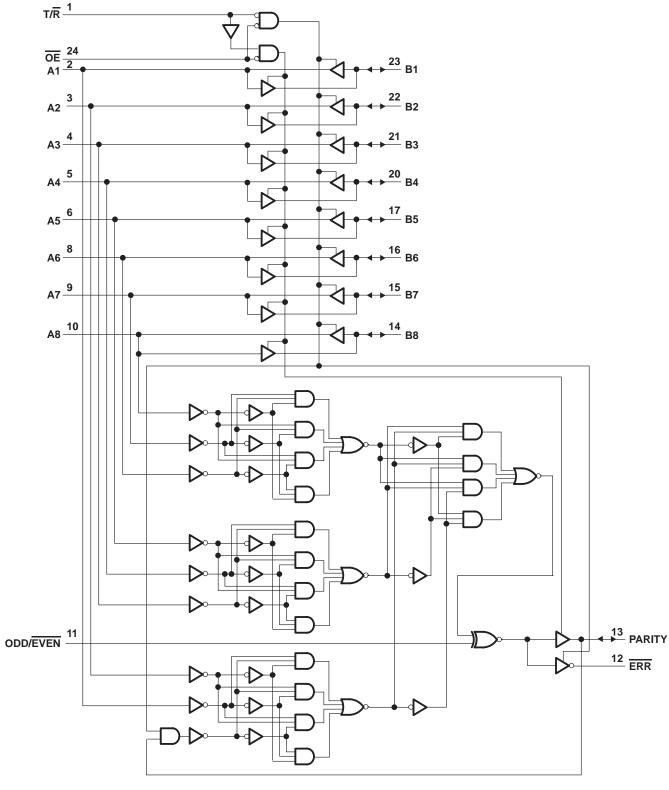
logic symbol†



 $[\]dagger$ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the DW, JT, and NT packages.



logic diagram (positive logic)



Pin numbers shown are for the DW, JT, and NT packages.



SCBS192E - JANUARY 1991 - REVISED JUNE 1997

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	0.5 V to 7 V
Input voltage range, V _I (except I/O ports) (see Note 1)	0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, VO	-0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT657A	96 mA
SN74ABT657A	128 mA
Input clamp current, I _{IK} (V _I < 0)	–18 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Package thermal impedance, θ _{JA} (see Note 2): DW package	81°C/W
NT package	67°C/W
Storage temperature range, T _{stg}	-65° C to 150° C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

recommended operating conditions (see Note 3)

			SN54AB	T657A	SN74AB	T657A	UNIT
			MIN	MAX	MIN	MAX	UNIT
VCC	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage		2	3	2		V
V _{IL}	Low-level input voltage			0.8		0.8	V
VI	Input voltage		0	Vcc	0	VCC	V
ІОН	High-level output current		7.	-24		-32	mA
loL	Low-level output current		2	48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled	20/	5		5	ns/V
Δt/ΔV _{CC}	Power-up ramp rate		200		200	·	μs/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

^{2.} The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

SCBS192E - JANUARY 1991 - REVISED JUNE 1997

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

$V_{IK} \qquad V_{CC} = 4.5 \text{ V}, \qquad I_{I} = -18 \text{ mA} \qquad -1.2 \qquad -1.2 \qquad -1.2 \qquad -1.2 \qquad V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -3 \text{ mA} \qquad 2.5 \qquad 2.5 \qquad 2.5 \qquad 2.5 \qquad V_{CC} = 5 \text{ V}, \qquad I_{OH} = -3 \text{ mA} \qquad 3 \qquad $	THAL	
$V_{OH} = \begin{array}{c ccccccccccccccccccccccccccccccccccc$	JNIT	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$		
$\begin{array}{ c c c c c c } \hline V_{CC} = 4.5 \ V & \begin{array}{ c c c c c } \hline I_{OH} = -24 \ mA & 2 & 2 \\ \hline I_{OH} = -32 \ mA & 2^* & 2 \\ \hline \hline V_{OL} & V_{CC} = 4.5 \ V & \begin{array}{ c c c c } \hline I_{OL} = 48 \ mA & 0.55 & 0.55 \\ \hline \hline V_{hys} & 100 & m \\ \hline \hline I_{I} & \begin{array}{ c c c } \hline Control \ inputs & V_{CC} = 0 \ to 5.5 \ V, \ V_I = V_{CC} \ or \ GND & \pm 1 & \pm 1 & \pm 1 \\ \hline A \ or \ B \ ports & V_{CC} = 2.1 \ V \ to 5.5 \ V, \ V_I = V_{CC} \ or \ GND & \pm 20 & \pm 20 \\ \hline \hline I_{OZPU}^{\ddagger} & \begin{array}{ c c } \hline V_{CC} = 0 \ to 2.1 \ V, \ V_O = 0.5 \ V \ to 2.7 \ V, \\ \hline \hline \hline I_{OZPD}^{\ddagger} & \begin{array}{ c c } \hline V_{CC} = 2.1 \ V \ to 5.5 \ V, \ V_O = 0.5 \ V \ to 2.7 \ V, \\ \hline \hline \hline \hline I_{OZ} = 2.1 \ V \ to 5.5 \ V, \ V_O = 2.7 \ V, \\ \hline \hline \hline \hline \hline I_{OZL} \\ \hline \hline \hline I_{OZL} \\ \hline \hline \hline \hline \hline \end{array} & \begin{array}{ c c } \hline V_{CC} = 2.1 \ V \ to 5.5 \ V, \ V_O = 0.5 \ V, \\ \hline $	V	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	V	
$\begin{array}{ c c c c c c c c } \hline V_{OL} & V_{CC} = 4.5 \text{ V} & \hline I_{OL} = 64 \text{ mA} & 0.55^* & 0.55 \\ \hline V_{hys} & 100 & m \\ \hline I_{I} & Control inputs & V_{CC} = 0 \text{ to } 5.5 \text{ V}, V_{I} = V_{CC} \text{ or GND} & \pm 1 & \pm 1 & \pm 1 \\ \hline A \text{ or B ports} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{I} = V_{CC} \text{ or GND} & \pm 20 & \pm 20 & \pm 20 \\ \hline I_{OZPU}^{\ddagger} & V_{CC} = 0 \text{ to } 2.1 \text{ V}, V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, & \pm 50 & \pm 50 & \pm 50 \\ \hline I_{OZPD}^{\ddagger} & V_{CC} = 2.1 \text{ V to } 0, V_{O} = 0.5 \text{ V to } 2.7 \text{ V}, & \pm 50 & \pm 50 & \pm 50 \\ \hline I_{OZH}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 2.7 \text{ V}, & 10 & 10 & 10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 \\ \hline I_{OZL}^{\$} & V_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, V_{O} = 0.5 \text{ V}, & -10 \\ \hline I_{OZL}^{\$} & V_{CC}^{*} & V_{CC}^{*}$		
$\begin{array}{ c c c c c c c c c c c c c c c c c c c$	V	
$\begin{array}{ c c c c c c c c } \hline I_{I} & \frac{\text{Control inputs}}{\text{A or B ports}} & \text{V}_{CC} = 0 \text{ to } 5.5 \text{ V}, \text{V}_{I} = \text{V}_{CC} \text{ or GND} & \pm 1 & \pm 1 & \pm 1 \\ \hline & \text{A or B ports} & \text{V}_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{I} = \text{V}_{CC} \text{ or GND} & \pm 20 & \pm 20 \\ \hline & \text{IOZPU}^{\ddagger} & \frac{\text{V}_{CC}}{\text{OE}} = 0 \text{ to } 2.1 \text{ V}, \text{V}_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \\ \hline & \text{IOZPD}^{\ddagger} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 0, \text{V}_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \\ \hline & \text{IOZH}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 2.7 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{OE} \geq 2 \text{ V} & -10 & -10 & -10 & -10 \\ \hline \end{array}$	V	
$\begin{array}{ c c c c c c c c } \hline I_{I} & \frac{\text{Control inputs}}{\text{A or B ports}} & \text{V}_{CC} = 0 \text{ to } 5.5 \text{ V}, \text{V}_{I} = \text{V}_{CC} \text{ or GND} & \pm 1 & \pm 1 & \pm 1 \\ \hline & \text{A or B ports} & \text{V}_{CC} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{I} = \text{V}_{CC} \text{ or GND} & \pm 20 & \pm 20 \\ \hline & \text{IOZPU}^{\ddagger} & \frac{\text{V}_{CC}}{\text{OE}} = 0 \text{ to } 2.1 \text{ V}, \text{V}_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \\ \hline & \text{IOZPD}^{\ddagger} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 0, \text{V}_{O} = 0.5 \text{ V to } 2.7 \text{ V}, \\ \hline & \text{IOZH}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 2.7 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{IOZL}^{\S} & \frac{\text{V}_{CC}}{\text{OE}} = 2.1 \text{ V to } 5.5 \text{ V}, \text{V}_{O} = 0.5 \text{ V}, \\ \hline & \text{OE} \geq 2 \text{ V} & -10 & -10 & -10 & -10 \\ \hline \end{array}$	mV	
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$		
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	μA	
$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	μΑ	
OZH^{\S} $OE ≥ 2 V$	μΑ	
$\overline{OE} \ge 2 \text{ V}$	μΑ	
	μΑ	
$oxed{I_{off}}$ $oxed{V_{CC}}=0,$ $oxed{V_{I}}$ or $oxed{V_{O}}\leq4.5oxed{V}$ ±100 ±100 μ	μΑ	
ICEX $V_{CC} = 5.5 \text{ V}, V_{O} = 5.5 \text{ V}$ Outputs high 50 50 μ	μΑ	
I_{O} ¶ $V_{CC} = 5.5 \text{ V}$, $V_{O} = 2.5 \text{ V}$ $-50 -100 -200$ $-50 -200$ $-50 -200$ m	mA	
$V_{CC} = 5.5 \text{ V},$ Outputs high 250 250 μ	μΑ	
$I_{O} = 0$, Outputs low 40 40 40 m	mΑ	
$V_I = V_{CC}$ or GND Outputs disabled 250 250 250 μ	μΑ	
Data inputs VCC = 5.5 V, One input at 3.4 V,		
I Uther inputs at I I I I I I I I I I I I I I I I I I	mA	
Control inputs $V_{CC} = 5.5 \text{ V}$, One input at 3.4 V, Other inputs at V_{CC} or GND 1.5 1.5		
C_i Control inputs $V_1 = 2.5 \text{ V or } 0.5 \text{ V}$	pF	
C _{io} A or B ports V _O = 2.5 V or 0.5 V 10	pF	

^{*} On products compliant to MIL-PRF-38535, this parameter does not apply.

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This parameter is characterized, but not production tested.

[§] The parameters IOZH and IOZL include the input leakage current.

[¶] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[#] This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

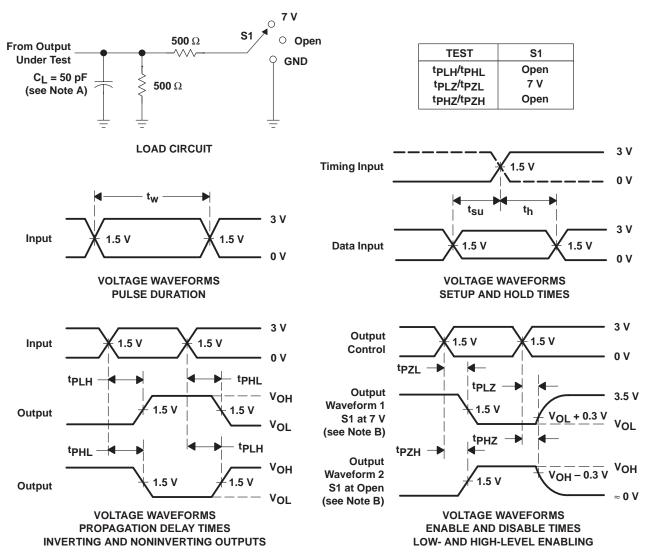
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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	۷ ₀ ۲ _/	C = 5 V \ = 25°C	/, ;	SN54AB	T657A	SN74AB	T657A	UNIT	
	(1141 01)	(0011 01)	MIN	TYP	MAX	MIN	MAX	MIN	MAX		
^t PLH	A or B	B or A	1	3.2	4.2	1	5	1	4.6	ns	
t _{PHL}	AOIB	BOIA	1	2.8	3.8	1	4.5	1	4.3	115	
^t PLH	А	PARITY	1.8	4.8	6.3	1.8	8.5	1.8	8.1	no	
t _{PHL}	A	PARITI	2.3	4.9	6.4	2.3	8.1	2.3	7.7	7.7 ns	
^t PLH	ODD (EVEN	DADITY FDD	1.1	3.3	4.2	1.1	5.3	1.1	4.9	ns	
t _{PHL}	ODD/EVEN	PARITY, ERR	1.3	3.4	4.5	1.3	5.1	1.3	4.9	116	
^t PLH	В		1.6	4.7	6.5	1.6	8.4	1.6	7.9	ns	
^t PHL	Ь	ERR	2.1	4.9	6.9	2.1	8	2.1	7.8	115	
^t PLH	PARITY	ERR	2	4.8	6.3	2	8.1	2	7.7	ns	
^t PHL	FANITI	EKK	2.1	4.9	6.7	2.1	8	2.1	7.5	115	
^t PZH	ŌĒ	A D DADITY	1.4	4	5.4	1.4	6.8	1.4	6.5	ns	
t _{PZL}	OE	A, B, PARITY	1.7	4.1	5.8	1.7	6.7	1.7	6.5	115	
^t PZH	ŌĒ		1.8	4.1	5.4	1.8	6.9	1.8	6.6	ns	
^t PZL	OE .	ERR	3.3	6.2	7.6	3.3	9.7	3.3	9.2	115	
^t PHZ	ŌĒ	A, B, PARITY, or	2.4	4.2	5.6	2.4	6.3	2.4	6.2	ns	
t _{PLZ}	OE .	ERR	1.8	4.2	6.2	1.8	8.9	1.8	7.8	115	

SCBS192E - JANUARY 1991 - REVISED JUNE 1997

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_Q = 50 \Omega$, $t_f \leq 2.5 \text{ ns.}$
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



PACKAGE OPTION ADDENDUM

www.ti.com 11-Nov-2009

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74ABT657ADBLE	OBSOLETE	SSOP	DB	24		TBD	Call TI	Call TI
SN74ABT657ADBR	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADBRE4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADBRG4	ACTIVE	SSOP	DB	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ADWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ABT657ANT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ABT657ANTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.



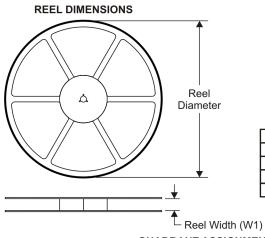
PACKAGE OPTION ADDENDUM

11-Nov-2009 www.ti.com In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

PACKAGE MATERIALS INFORMATION

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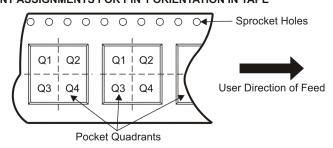
TAPE AND REEL INFORMATION





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		Dimension designed to accommodate the component width
Γ	B0	Dimension designed to accommodate the component length
	K0	Dimension designed to accommodate the component thickness
	W	Overall width of the carrier tape
Γ	P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT657ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT657ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT657ADBR	SSOP	DB	24	2000	346.0	346.0	33.0
SN74ABT657ADWR	SOIC	DW	24	2000	346.0	346.0	41.0

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